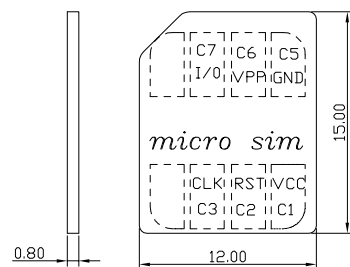
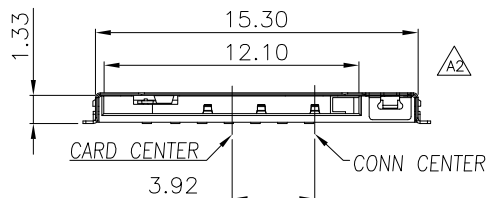
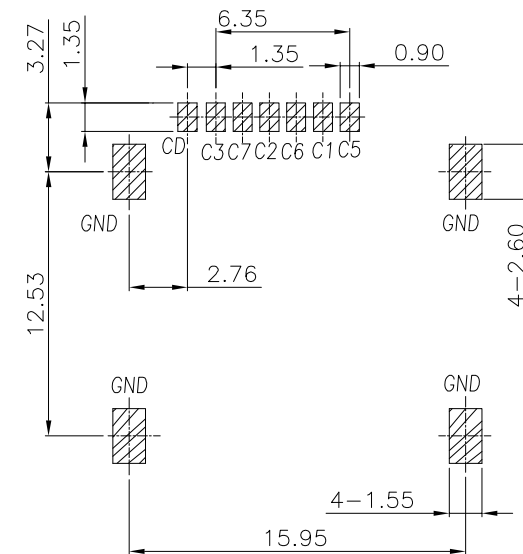
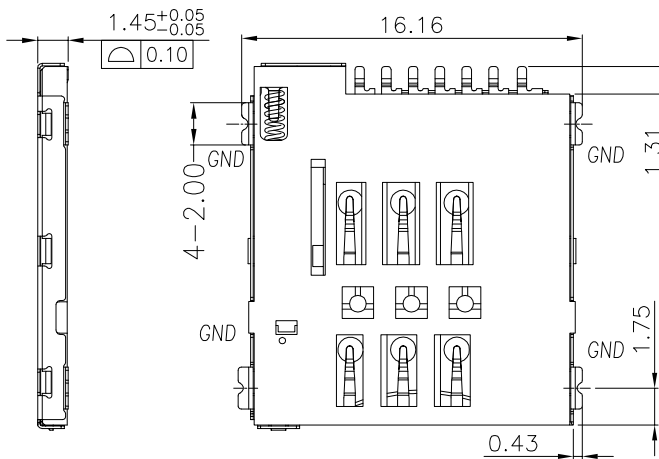
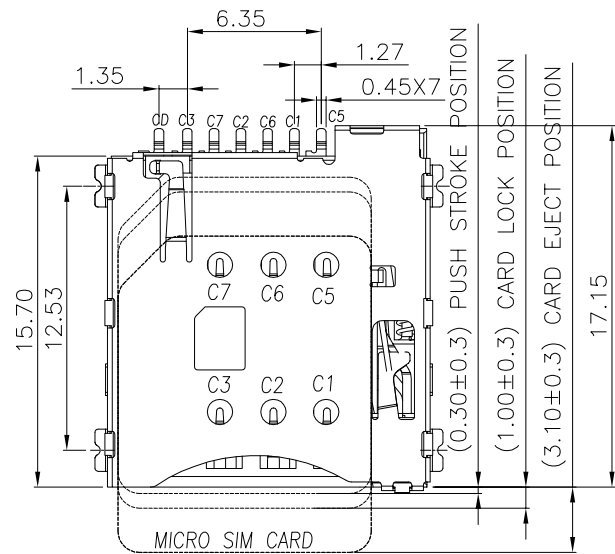


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A0		NEW	2017/10/13
A1		增加扣点	2020/04/29



MICRO SIM CARD

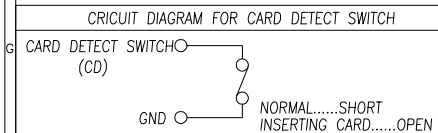
NOTES:

- 1)MATERIAL:
HOUSING: LCP, PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL

- 2)FINISH:
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,

■ CIRCUIT TRACE KEEP OUT AREA
▨ SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



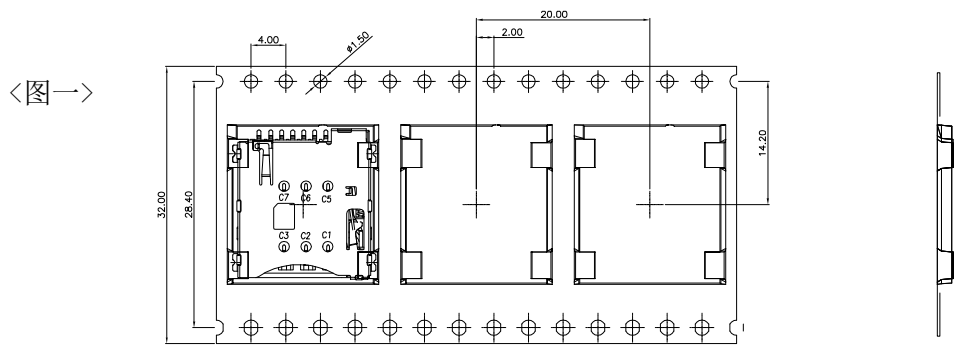
SIM pin Assignment		GENERAL TOLERANCE		DWG NO.	APPD:	WIND	Scale	1:1
PIN#	Name	X.±0.45	x.*±5°	Title	CHKD:		UNIT	mm
C1	VCC	.X±0.35	.x.*±2°	MICRO SIM CARD PUSH PUSH 7PIN 1.45H 带CD PIN(防呆型)	DR:		UNIT	mm
C2	RST	.XX±0.25	.xx.*±1°		Date	2017/10/13		
C3	CLK	.XXX±0.15	.xxx.*±0.5°					
C5	GND							
C6	VPP							
C7	I/O							
		SHEET	1/2					

JYSCONN

Shenzhen

JYSCONN Electronics Co., LTD.

REV.	ECN.NO.	MODIFY.CONTENT	DATE
AO		图面首次发行	2017/10/13

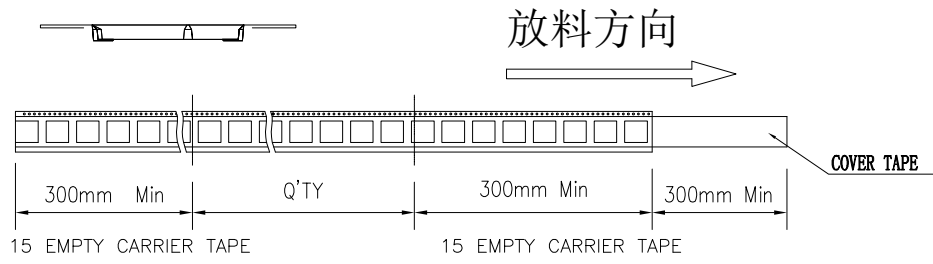


<图一>

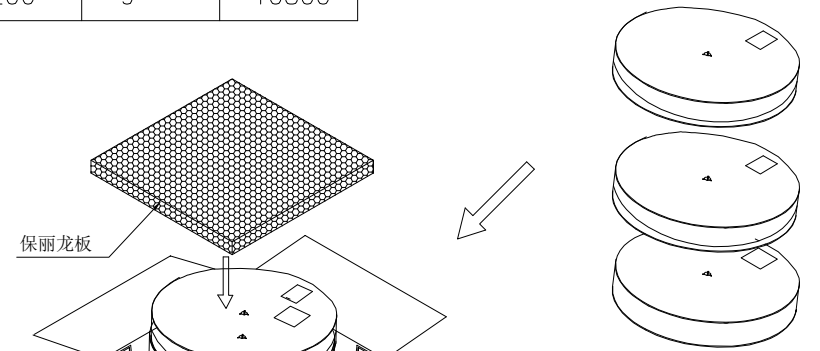
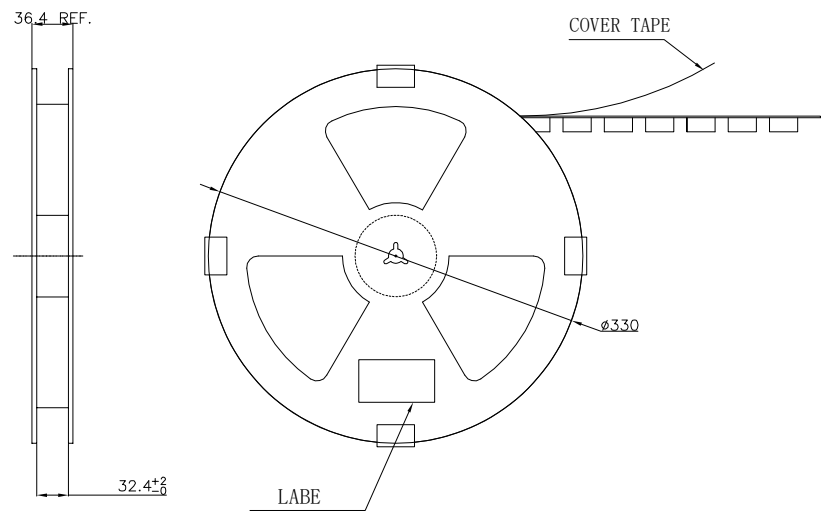
<图三>

<TABLE 1> PACKAGING QUANTITY

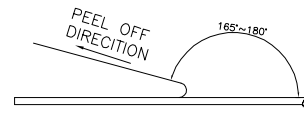
QTY/REEL	REEL/CARTON	QTY/CARTON
1200	9	10800



<图二>

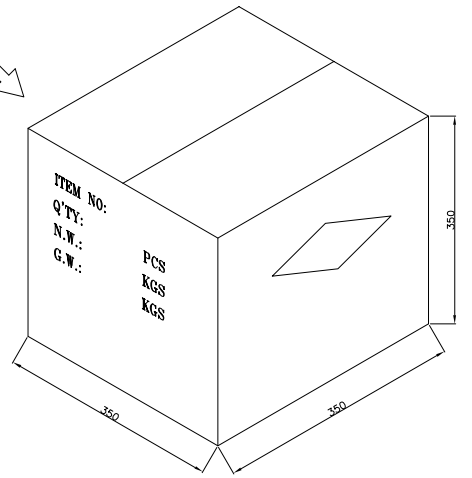


COVER TAPE PEELING FORCE: 20gf~100gf



NOTE:

- 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
- 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
- 包装数量见如<TABLE 1>示
- 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
- 封箱, 在封好的纸箱上按客户要求写上料号, 数量等



GENERAL TOLERANCE		图号	设计	彭善平	比例	1:1
X.±0.45	x.±5°	品名	MICRO SIM CARD PUSH PUSH	审核	单位	mm
.X±0.35	.x±2°		7PIN 1.45H 带CD PIN(防呆型)	核准		
.XX±0.25	.xx±1°	料号	JYS-SIM145-198	日期	2017/10/13	
.XXX±0.15	.xxx±0.5°					
页号	2/2	JYSCONN Electronics Co., LTD.				